CORRECTED VERSION

(19) World Intellectual Property Organization

International Bureau

OMP





(10) International Publication Number WO 2007/101138 A2

(43) International Publication Date 7 September 2007 (07.09.2007)

- (51) International Patent Classification: *HOLL 31/00* (2006.01)
- (21) International Application Number:

PCT/US2007/062766

(22) International Filing Date:

23 February 2007 (23.02.2007)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

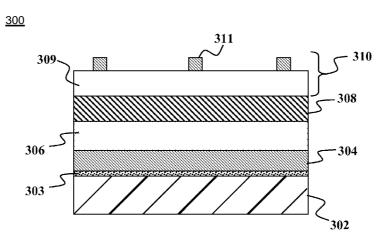
11/361,433	23 February 2006 (23.02.2006)	US
11/361,497	23 February 2006 (23.02.2006)	US
11/361,515	23 February 2006 (23.02.2006)	US
11/361,103	23 February 2006 (23.02.2006)	US
11/361,521	23 February 2006 (23.02.2006)	US
11/361,522	23 February 2006 (23.02.2006)	US
11/394,849	30 March 2006 (30.03.2006)	US
11/395,438	30 March 2006 (30.03.2006)	US
11/395,668	30 March 2006 (30.03.2006)	US

- (71) Applicants and
- (72) Inventors: VAN DUREN, Jeroen, K., J. [NL/US]; 903 Fremont Street, Menlo Park, CA 94025 (US). LEI-DHOLM, Craig, R. [US/US]; 934 La Mesa Terrace, Sunnyvale, CA 94086 (US).

- (72) Inventor; and
- (75) Inventor/Applicant (for US only): ROBINSON, Matthew, R. [US/US]; 2440 Embarcadero Way, Palo Alto, CA 94303 (US).
- (74) Agent: TUNG, Hao, Y.; 2440 Embarcadero Way, Palo Alto, CA 94303 (US).
- (81) **Designated States** (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, **BR**, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FT, GB, GD, GE, GH, GM, GT, HN, **HR**, HU, **ID**, IL, IN, IS, **JP**, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Continued on next page]

(54) Title: HIGH-THROUGHPUT PRINTING OF SEMICONDUCTOR PRECURSOR LAYER FROM INTER-METALLIC NANOFLAKE PARTICLES



(57) Abstract: Methods and devices are provided for transforming non-planar or planar precursor materials in an appropriate vehicle under the appropriate conditions to create dispersions of planar particles with stoichiometric ratios of elements equal to that of the feedstock or precursor materials, even after selective forces settling. In particular, planar particles disperse more easily, , form much denser coatings (or form coatings with more interparticle contact area), and anneal into fused, dense films at a lower temperature and/or time than their counterparts made from spherical nanoparticles. These planar particles may be nanoflakes that have a high aspect ratio. The resulting dense films formed from nanoflakes are particularly useful in forming photovoltaic devices. In one embodiment, at least one set of the particles in the ink may be inter-metallic flake particles (microflake or nanoflake) containing at least one group IB-IIIA inter-metallic alloy phase.



WO 2007/101138 A2



Published:

 without international search report and to be republished upon receipt of that report

(48) Date of publication of this corrected version:

6 December 2007

(15) Information about Correction:

see PCT Gazette No. 49/2007 of 6 December 2007

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.